

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**1 (currently amended).** A solder paste printing method comprising:

a first process for mounting a mask having apertures corresponding to land portions of a printed circuit board, on said printed circuit board at a predetermined position thereof in a state where it is placed in position;

a second process for mounting a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder on said mask and for permitting said solder paste to make rolling from one end of said mask toward the opposite end thereof by means of a squeegee, while maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said ~~squeegee urges~~ squeegee urges said solder paste to make rolling, to thereby fill said solder paste into said apertures; and

a third process for separating said mask away from said printed circuit board.

**2 (original).** The solder paste printing method according to claim 1, wherein said moisture is equal to or less than  $10 \text{ g/m}^3$ .

**3 (original).** The solder paste printing method according to claim 2, wherein said atmosphere mainly comprises a nitrogen gas ( $\text{N}_2$ ).

**4 (original).** A solder paste printing apparatus comprising:

a mask having apertures corresponding to land portions of a printed circuit board;

a squeegee urging a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder and mounted on said mask, which is placed in position at a predetermined position on said printed circuit board to make rolling from one end of said mask toward the opposite end thereof; and

a moisture regulating means for maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value.

**5 (currently amended).** The solder paste printing apparatus according to claim 4, wherein said moisture regulating means is designed to regulate moisture to a degree equal to or less than 10 g/m<sup>3</sup>.

**6 (currently amended).** The solder paste printing apparatus according to claim 5, wherein said atmosphere mainly comprises a nitrogen gas (N<sub>2</sub>) supplied by a gas source.